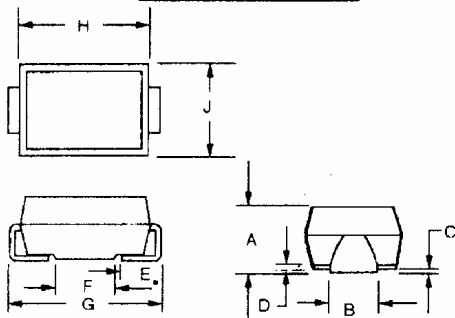
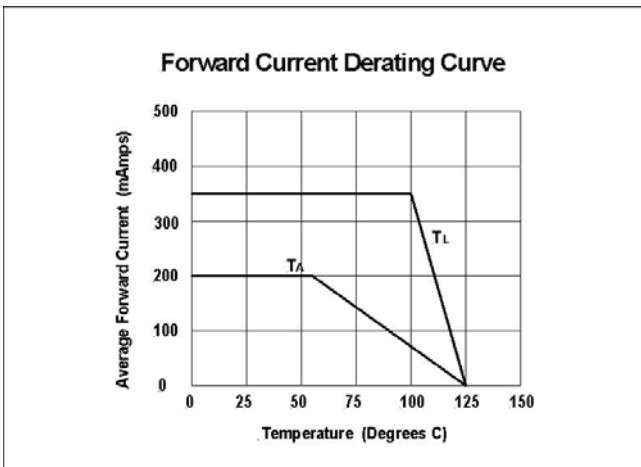


SMA/DO-214AC



DIMENSIONS				
	inches		mm	
	Min	Max	Min	Max
A	0.078(L)	0.116(L)	1.98(L)	2.96(L)
A	0.110(H)	0.117(H)	2.80(H)	2.98(H)
B	0.067	0.088	1.7	2.24
C		0.008		0.20
D		0.02		0.51
E	0.030	0.060	0.76	1.52
F	0.065	0.094	1.65	2.39
G	0.204	0.220	5.21	5.59
H	0.160	0.180	4.06	4.57
I	0.101	0.112	2.56	2.85



NOTETHIS IS A PRELIMINARY DATA SHEET AND IS SUBJECT TO CHANGE****

Surface Mount High Voltage Diode

SM3F		
Repetitive Peak Reverse Voltage	V_{RRM}	3,000 Volts
Average Forward Current Max @ $T_A=55^{\circ}C$	I_{FAVM}	200 mAmps
Average Forward Current Max @ $T_L=100^{\circ}C$	I_{FAVM}	350 mAmps
Maximum Forward Voltage Drop, @ $I_F=100$ mAmps	V_F	3.0 Volts
Maximum Reverse Current @ V_{RRM} @ $25^{\circ}C$	I_R	5.0 μ Amps
Typical Reverse Recovery Time @ $I_F=20$ mA, $I_R=40$ mA, $I_{tr}=10$ mA	T_{RR}	75 nsec
Typical Reverse Recovery Time @ $I_F=5$ mA, $I_R=10$ mA, $I_{tr}=2.5$ mA	T_{RR}	100 nsec
Maximum Surge Current (8.3ms Sine Wave)	I_{FSM}	15 Amps
Typical Junction Capacitance (NOTE 1)	C_J	15 pF
Typical Thermal Resistance (NOTE 2)	$R_{\theta JA}$	30 $^{\circ}C/W$
Typical Thermal Resistance (NOTE 2)	$R_{\theta JL}$	7 $^{\circ}C/W$
Operating Temperature	T_A	-35 $^{\circ}C$ to 125 $^{\circ}C$
Storage Temperature	T_{STG}	-55 $^{\circ}C$ to 150 $^{\circ}C$

NOTES:

- (1) Measured at 1kHz
- (2) Thermal resistance from junction to ambient and from junction to lead P.C.B. mounted on 0.2" x 0.2" (5.0 x 5.0mm) copper pad areas